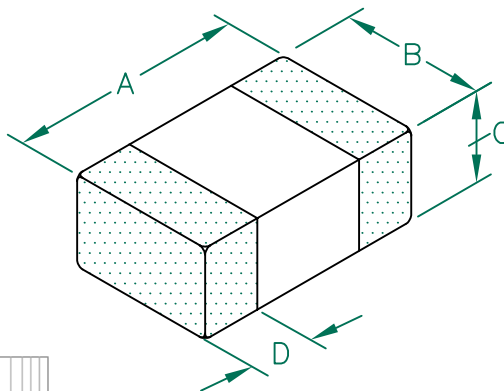


CPI0805E3R3R-10

UNCONTROLLED DOCUMENT

PHYSICAL DIMENSIONS:

A	2.00 [.079]	+ 0.20 [.008]
B	1.25 [.049]	+ 0.20 [.008]
C	0.90 [.035]	+ 0.10 [.004]
D	0.50 [.020]	+ 0.20 [.008]



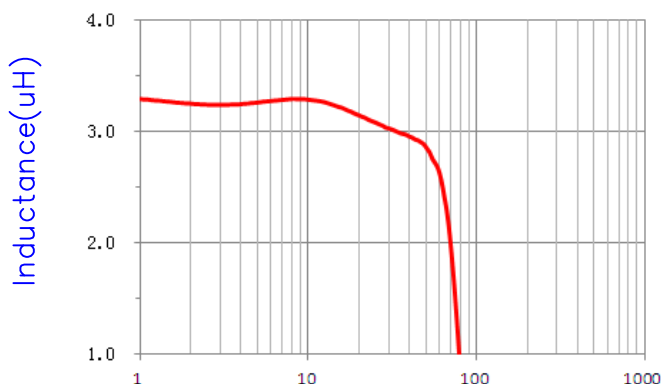
ELECTRICAL CHARACTERISTICS:

	L (μ H) @ 1MHz $\pm 20\%$	DCR (Ω) $\pm 25\%$	I (Max)
Nom	3.3	0.22	
Min	2.6	0.165	
Max	4.0	0.275	500mA

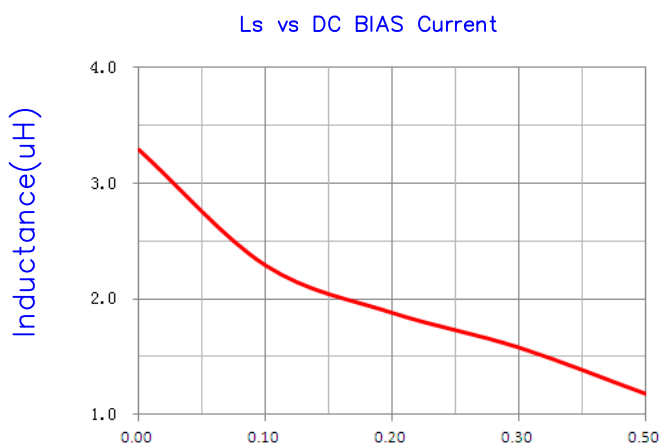
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. OPERATING TEMPERATURE TEMP: -55°C ~ +125°C (INCLUDING SELF-HEATING)

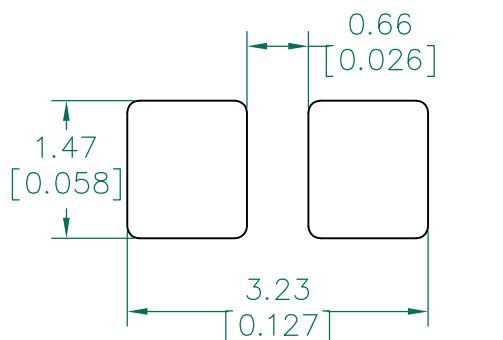
Ls vs Frequency



Ls vs DC BIAS Current

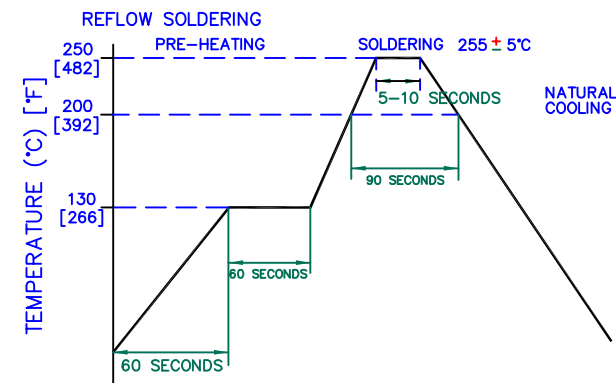


LAND PATTERNS FOR REFLOW SOLDERING



[0.030] to this dimension)
(For wave soldering, add 0.763)

RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES].

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PROJECT/PART NUMBER:				REV	PART TYPE:	DRAWN BY:
C	CHANGE PLASTIC TAPE TO PAPER TAPE	04/17/14	QU	C	CO-FIRE	QU
B	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE:	03/01/11	SCALE: NTS
A	ORIGINAL DRAFT	03/01/11	QU	CAD #	CPI0805E3R3R-10-A	SHEET: 1 of 1
REV	DESCRIPTION	DATE	INT	TOOL #	-	